L Number	Hits	Search Text	DB	Time stamp
3	128	mount\$3 with system and board with	USPAT;	2003/11/05
١	120	electrode and (inspect\$3 detect\$3) and	EPO; JPO	13:29
		solder\$3 and print\$3	EFO, OFO	13.29
4	23		USPAT;	2003/11/05
4	23		•	1
		electrode with (inspect\$3 detect\$3) and	EPO; JPO	14:30
	۔	solder\$3 and print\$3		2000/11/05
8	5	mount\$3 with system and board near2	USPAT;	2003/11/05
		(inspect\$3 detect\$3) with unit and	EPO; JPO	14:30
		electrode and solder\$3 and print\$3		
-	3	(component adj1 mounting).ti. and	USPAT;	2003/07/11
l i		(inoue).in.	US-PGPUB	16:02
-	838	1 - '	USPAT;	2003/06/26
		mount\$3 and controll\$3 and component and	EPO; JPO	16:10
1		detect\$3		
-	747	\L ===== = ===== ===== = ====== = ======	USPAT;	2003/06/26
		mount\$3 and controll\$3 and component and	EPO; JPO	16:11
		detect\$3) and system		
-	719	((print\$3 and inspect\$3 and solder\$3 and	USPAT;	2003/06/26
		mount\$3 and controll\$3 and component and	EPO; JPO	16:11
		detect\$3) and system) and (board		
		substrate card)		
-	68	(((print\$3 and inspect\$3 and solder\$3 and	USPAT;	2003/06/26
		mount\$3 and control1\$3 and component and	EPO; JPO	16:23
		detect\$3) and system) and (board		
		substrate card)) and 29/\$.ccls.		
-	35		USPAT;	2003/06/26
		mount\$3 and controll\$3 and component and	EPO; JPO	16:26
1		detect\$3) and system) and (board		[
		substrate card)) and 361/\$.ccls.		
l –	19	(((print\$3 and inspect\$3 and solder\$3 and	USPAT;	2003/06/26
		mount\$3 and controll\$3 and component and	EPO; JPO	16:28
		detect\$3) and system) and (board	,	
i		substrate card)) and 174/\$.ccls.		
_	187	(((print\$3 and inspect\$3 and solder\$3 and	USPAT;	2003/06/26
		mount\$3 and control1\$3 and component and	EPO; JPO	16:56
		detect\$3) and system) and (board		
		substrate card)) and electrode		
_	2	print\$3 and inspect\$3 adj1 unit and	USPAT;	2003/06/26
	_	(mounting mount) and pick\$3 and plac\$3	EPO; JPO	16:59
		and solder\$3 and electrode		
_	0	print\$3 and inspect\$3 and mounting adj1	USPAT;	2003/06/26
		system and pick\$3 and plac\$3 and solder\$3	EPO; JPO	16:59
		and electrode	,	
_	17	print\$3 and inspect\$3 and mounting adj1	USPAT;	2003/06/26
į į		system and electrode	EPO; JPO	17:00
_	109	component adj1 mounting with system and	USPAT;	2003/07/11
		inspect\$3	US-PGPUB	16:03
_	75	component adj1 mounting with system and	USPAT;	2003/07/11
		inspect\$3	EPO; JPO	16:21
_	88	component adj1 mounting and system and	USPAT;	2003/07/11
		inspect\$3 and solder\$3 and print\$3	EPO; JPO	16:22
-	60	(component adj1 mounting and system and	USPAT;	2003/07/11
ļ l		inspect\$3 and solder\$3 and print\$3) and	EPO; JPO	16:23
}		control\$4		
_	19	board with inspection with unit and	USPAT;	2003/11/04
		solder\$3 and mount\$3 and controller	EPO; JPO	17:09
_	32	228/\$.ccls. and 29/\$.ccls. and component	USPAT;	2003/11/05
	32	with mount\$3 with system	EPO; JPO	10:14
<u> </u>	294	228/\$.ccls. and solder\$3 and component	USPAT;	2003/11/05
	294	and mount\$3 with system	EPO; JPO	10:09
_	114			2003/11/05
-	114	(228/\$.ccls. and solder\$3 and component	USPAT;	
		and mount\$3 with system) and (inspect\$3	EPO; JPO	10:10
_	94	detect\$4)	IICDAM -	2002/11/05
-	94	solder\$3 and 29/\$.ccls. and component	USPAT;	2003/11/05
		with mount\$3 with system and (inspect\$3	EPO; JPO	10:15
L		detect\$4)		l